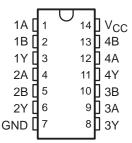
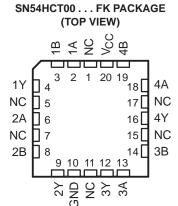
- Operating Voltage Range of 4.5 V to 5.5 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I_{CC}

SN54HCT00 . . . J OR W PACKAGE SN74HCT00 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Typical t_{pd} = 10 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible



NC - No internal connection

description/ordering information

These devices contain four independent 2-input NAND gates. They perform the Boolean function $Y = \overline{A} \bullet \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

TA	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HCT00N	SN74HCT00N
		Tube of 50	SN74HCT00D	
	SOIC - D	Reel of 2500	SN74HCT00DR	HCT00
		Reel of 250	SN74HCT00DT	
–40°C to 85°C	SOP - NS	Reel of 2000	SN74HCT00NSR	HCT00
	SSOP – DB	Reel of 2000	SN74HCT00DBR	HT00
		Tube of 90	SN74HCT00PW	
	TSSOP – PW	Reel of 2000	SN74HCT00PWR	HT00
		Reel of 250	SN74HCT00PWT	
	CDIP – J	Tube of 25	SNJ54HCT00J	SNJ54HCT00J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HCT00W	SNJ54HCT00W
	LCCC – FK	Tube of 55	SNJ54HCT00FK	SNJ54HCT00FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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FUNCTION TABLE (each gate)

INP	JTS	OUTPUT
Α	В	Υ
Н	Н	L
L	X	Н
Х	L	Н

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5	V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)		±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)		±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})			±25 mA
Continuous current through V _{CC} or GND			±50 mA
Package thermal impedance, θ _{JA} (see Note 2):	D package		86°C/W
,	DB package		96°C/W
	N package		80°C/W
	NS package		76°C/W
	PW package		113°C/W
Storage temperature range, T _{stg}	· · · · · · · · · · · · · · · · · · ·	-65°C	to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 3)

			SN	154HCT	00	SN	174HCT0	00	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	\$ 5.5	4.5	5	5.5	V
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2	,S	1/5	2			V
V _{IL}	Low-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		J. J.	0.8			0.8	V
٧ _I	Input voltage		0	1	VCC	0		VCC	V
VO	Output voltage		0	2	VCC	0		VCC	V
Δt/Δν	Input transition rise/fall time		Q ₂	5	500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	NOITIONS	V	Т	A = 25°C	;	SN54F	ICT00	SN74H	ICT00	UNIT
PARAMETER	TEST COI	NDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Va.:	\\. = \\ or \\	I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		V
VOH	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
Voi	VI = VIH or VIL	I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	V
VOL	VOL $VI = VIH or VIL$		4.5 V		0.17	0.26		0.4		0.33	٧
lį	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100	,4	±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	5.5 V			2	ζο,	40		20	μΑ
ΔI _{CC} †	One input at 0.5 V one of the		5.5 V		1.4	2.4	goy.	3		2.9	mA
Ci			4.5 V to 5.5 V		3	10	7	10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or VCC.

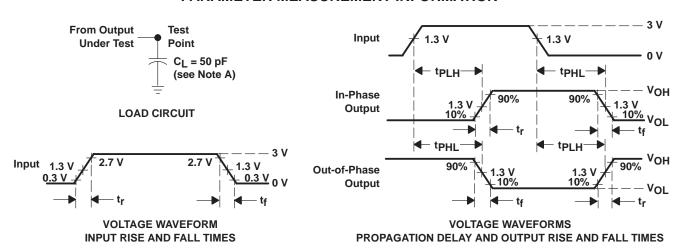
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	Vaa	T,	ղ = 25°C	;	SN54HCT00	SN74F	ICT00	UNIT
TANAMETER	(INPUT)		Vcc	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
	A or P	V	4.5 V		11	20	(3)		25	no
¹рd	t _{pd} A or B	T	5.5 V		10	18	0/2/2	·	22	ns
		V	4.5 V		9	15	P 2:	2	19	
it		Ť	5.5 V		8	14	20		17	ns

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	20	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



11-Nov-2021

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HCT00D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT00	Samples
SN74HCT00DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HT00	Samples
SN74HCT00DBRE4	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HT00	Samples
SN74HCT00DE4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT00	Samples
SN74HCT00DG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT00	Samples
SN74HCT00DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HCT00	Samples
SN74HCT00DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT00	Samples
SN74HCT00DT	ACTIVE	SOIC	D	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT00	Samples
SN74HCT00N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HCT00N	Samples
SN74HCT00NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HCT00N	Samples
SN74HCT00NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT00	Samples
SN74HCT00PW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HT00	Samples
SN74HCT00PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HT00	Samples
SN74HCT00PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HT00	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS**: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".



PACKAGE OPTION ADDENDUM

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RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT00DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74HCT00DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HCT00DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HCT00DT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HCT00NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HCT00PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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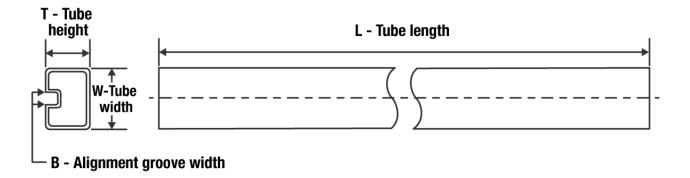
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT00DBR	SSOP	DB	14	2000	853.0	449.0	35.0
SN74HCT00DR	SOIC	D	14	2500	340.5	336.1	32.0
SN74HCT00DR	SOIC	D	14	2500	853.0	449.0	35.0
SN74HCT00DT	SOIC	D	14	250	210.0	185.0	35.0
SN74HCT00NSR	SO	NS	14	2000	853.0	449.0	35.0
SN74HCT00PWR	TSSOP	PW	14	2000	853.0	449.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

All difficusions are nominal								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HCT00D	D	SOIC	14	50	506.6	8	3940	4.32
SN74HCT00DE4	D	SOIC	14	50	506.6	8	3940	4.32
SN74HCT00DG4	D	SOIC	14	50	506.6	8	3940	4.32
SN74HCT00N	N	PDIP	14	25	506	13.97	11230	4.32
SN74HCT00N	N	PDIP	14	25	506	13.97	11230	4.32
SN74HCT00NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74HCT00NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74HCT00PW	PW	TSSOP	14	90	530	10.2	3600	3.5

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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